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TITLE : ANTIMICROBIAL ADDITIVE FOR RESIN AND MOLDING OF ANTIMICROBIAL RESIN

ABSTRACT : PURPOSE: To mold an antimicrobial resin by dispersing an antimicrobial material such as a compound of silver, copper or zinc in a liquid dispersion medium to prepare an antimicrobial additive, adding it to a natural resin pellet, kneading and melting the resultant mixture and injection-molding it into a mold.

CONSTITUTION: This antimicrobial additive for resin is prepared by dispersing an antimicrobial material such as an inorganic antimicrobial agent or a heat-resistant organic antimicrobial agent in a liquid dispersion medium such as liquid paraffin or a silicone oil. As the antimicrobial material, a compound of a metal selected from silver, copper and zinc, especially thiosulfatosilver complex supported by silica gel is preferably used. If a natural resin pellet blended with this additive is kneaded, melted and subsequently injection-molded into a mold, an antimicrobial resin mold is obtained. In this molding method, a resin coloring additive composed of a pigment dispersed together with a dispersant in a liquid dispersion medium can be admixed with the natural resin pellet as necessary. This method can produce a resin molding having a practical antimicrobial property by ready operations.

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